

### **Customer Information Notification**

202201007I: NXP Standardized Tray Attributes for LQFP 10x10 Bulk

**Shipments** 

Note: This notice is NXP Company Proprietary.				
Issue Date: Feb 08, 2022 Effective date:Mar 08, 2022 Change Category				
Wafer Fab Process	Assembly Process	Product Marking	Test Process	Design
Wafer Fab Materials	Assembly Materials	☐ Mechanical Specification	Test Equipment	□ Errata
Wafer Fab Location	Assembly Location  Other	Packing/Shipping/Labeling	☐ Test Location	Electrical spec./Test coverage
PCN Overview				

# **Description**

NXP Semiconductors announces a Standardized Tray Supplier Initiative for the tray configuration bulk shipments of LQFP 10x10 devices associated with this notification. The new tray initiative results in standardized tray attributes, by package size, to allow manufacturing consolidation and avoid different tray vendor mixture issues for customers. This standardized tray initiative can be rolled out across different NXP package types / sizes as future opportunities present.

Minor change only to tray attributes, including:

<sup>\*\*</sup> No change to tray critical dimensions \*\*

- End tab embossment: Change from Peak to NXP logo
- Tray temp: Meet or exceed current tray value
- Color stripe: Change from no color stripe to Blue color stripe

Even though no change to bulk tray critical dimensions, Customer Information Notification 202201007I is issued to ensure no customer manufacturing disruption upon NXP implementation of new standardized tray for LQFP 10x10 devices purchased in tray configuration from NXP. Upon notification Effective Date, LQFP 10x10 products will begin ramped implementation shipments to customers with new tray attributes.

Please Note: During new standardized tray ramped introduction, it is recommended to not mix or stack different tray types.

Please see attached information for tray change details.

For Automotive Customers: Corresponding ZVEI Delta Qualification Matrix ID: SEM-PS-03 **Reason** 

Standardized tray, by package size, to allow manufacturing consolidation, and avoid different tray vendor mixture issues for customers of NXP tray product shipments.

#### **Identification of Affected Products**

Product identification does not change

No change to NXP orderable part number / 12NC.

Minor change only to tray attributes - see attached information for tray change details.

## Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

#### **Disposition of Old Products**

Existing inventory will be shipped until depleted

#### Additional information

Additional documents: view online

## **Contact and Support**

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

#### **About NXP Semiconductors**

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**NXP Semiconductors** 

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